

# **SPECIFICATION**

## **Chip Antenna**

**Model No. : SENA\_003**

<b>WRITTEN</b>	<b>CHECKED</b>	<b>APPROVED</b>
	<b>Seunghyun Kim</b>	<b>Seunghyun Kim</b>

**July 22, 2009**

### **Notes**

**The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.**

# 1. SPECIFICATIONS

## 1.1. Electrical Specifications

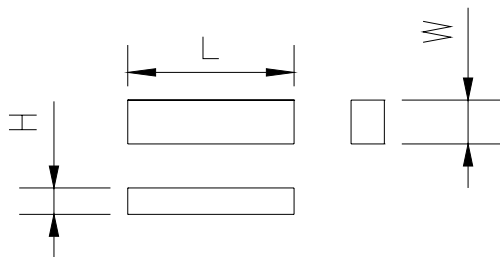
ITEM	SPEC.	Unit
Frequency	2400-2485	MHz
Bandwidth @ VSWR 2.5:1	100	MHz
Gain Max.	0.3	dBi
Polarization	Linear	
Azimuth Beam Pattern	Omni-directional	
Impedance	50	$\Omega$

※ These values are measured on the matched reference test board.

## 1.2. Mechanical Specifications

Electrode	Silver	
Dimensions (L x W x H)	9.0 x 3.0 x 1.2	mm
Operating Temperature	-35 ~ +85	°C

## 1.3. Appearance and Dimensions



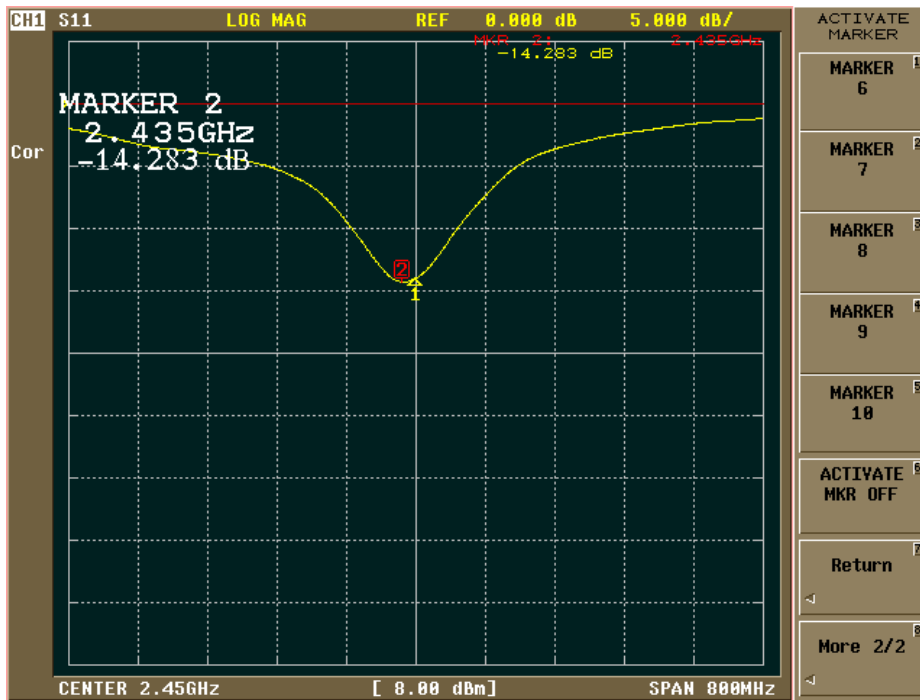
- unit : mm  
- Tolerance :  $\pm 0.15$

L	9.0
W	3.0
H	1.2

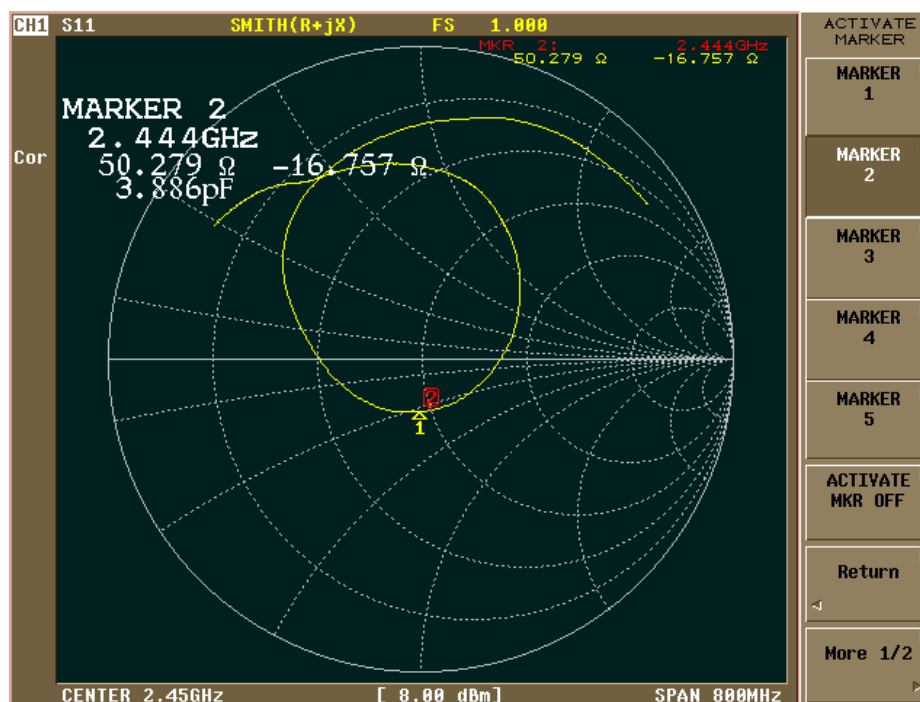
## 2. MEASUREMENT

### 2.1. Electrical Characteristic

#### A. $S_{11}$ (Return Loss)

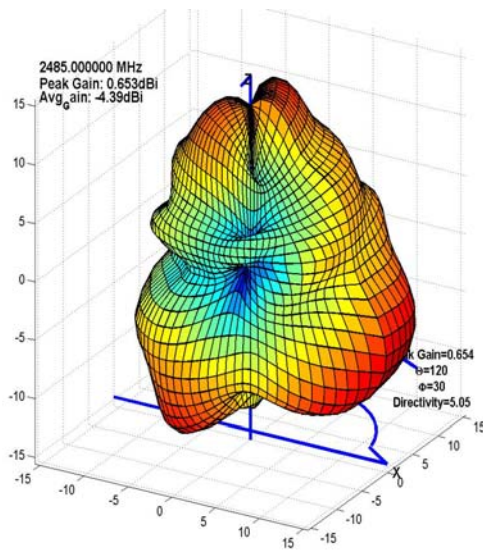
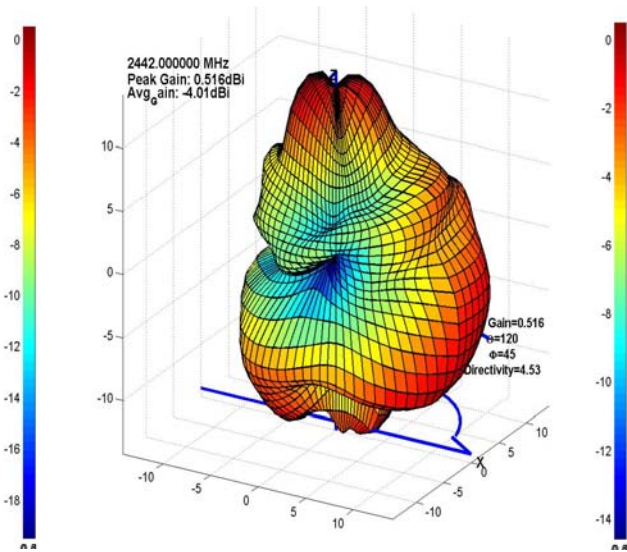
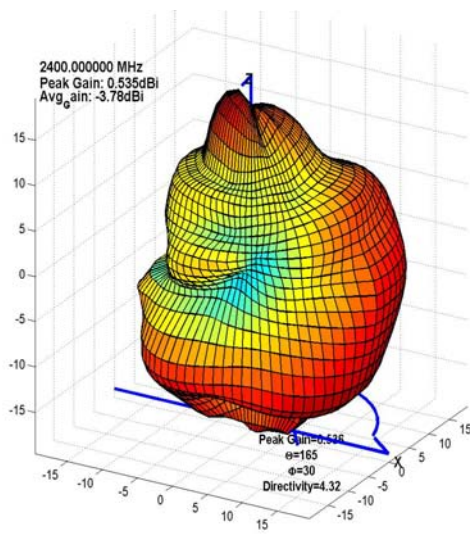


#### B. $S_{11}$ (Smith chart)

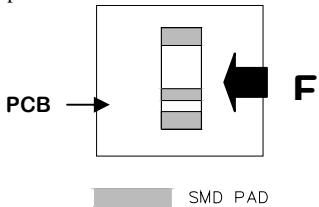


### 3. Radiation Data

Frequency	Efficiency	Average Gain			Max Gain			Max Position	Directivity
		Ver	Hor	Total	Ver	Hor	Total		
2400 MHz	41.8 %	-7.0 dBi	-6.6 dBi	-3.8 dBi	0.3 dBi	-0.8 dBi	0.1 dBi	Theta165/Pie30	4.32 dB
2442 MHz	39.7 %	-6.9 dBi	-7.2 dBi	-4.0 dBi	-0.2 dBi	-1.6 dBi	0.3 dBi	Theta120/Pie45	4.53 dB
2485 MHz	36.3 %	-7.1 dBi	-7.7 dBi	-4.4 dBi	-2.2 dBi	-1.6 dBi	0.2 dBi	Theta120/Pie30	5.05 dB



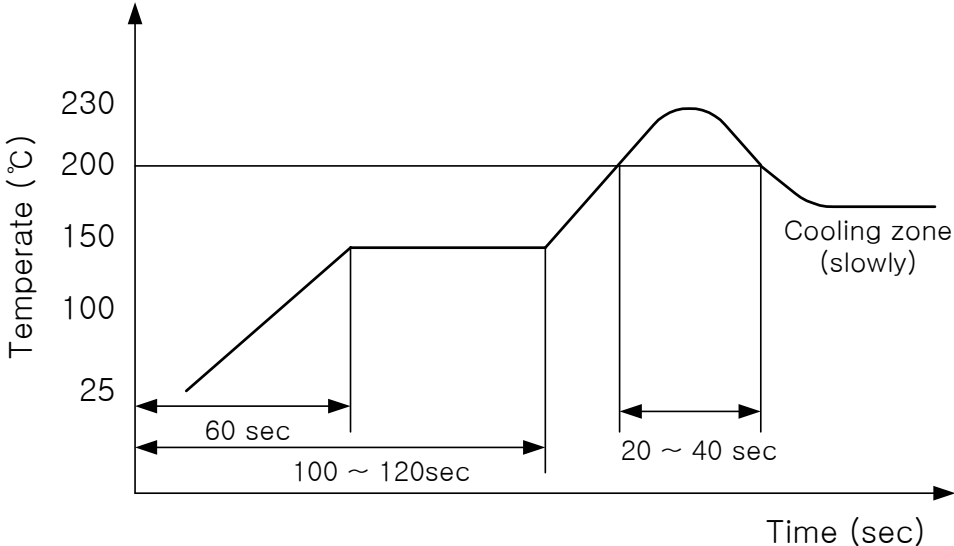
## 4. RELIABILITY TEST

No	Item	Test condition	Test Requirements
1	Adhesion strength	<p>. Applied force on SMD chip till detached point from PCB</p>  <p>PCB →</p> <p>← F</p> <p>■ SMD PAD</p>	<ol style="list-style-type: none"> <li>1. No mechanical damage by forces applied on the right</li> <li>2. Strength (F) &gt; 5 kgf</li> </ol>
2	Thermal Shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>1. 1 cycle / step 1 : <math>-40 \pm 3^{\circ}\text{C}</math>, 30 min step 2 : <math>+85 \pm 3^{\circ}\text{C}</math>, 30 min</li> <li>2. Number of cycle : 10</li> <li>3. Measure after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>1. No visual damage</li> <li>2. VSWR satisfy</li> </ol>
3	High Temperature Resistance	<ol style="list-style-type: none"> <li>1. Temperature: <math>+85 \pm 5^{\circ}\text{C}</math></li> <li>2. Time : 96 hrs</li> <li>3. Measure VSWR<sub>C</sub> after left for 24 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>1. No visual damage</li> <li>2. VSWR satisfy</li> </ol>
4	Low Temperature Resistance	<ol style="list-style-type: none"> <li>1. Temperature: <math>-40 \pm 5^{\circ}\text{C}</math></li> <li>2. Time : 96 hrs</li> <li>3. Measure VSWR<sub>C</sub> after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>1. No visual damage</li> <li>2. VSWR satisfy</li> </ol>
5	Humidity (Steady Condition)	<ol style="list-style-type: none"> <li>1. Humidity : 85 % RH</li> <li>1. Temperature: <math>+85 \pm 3^{\circ}\text{C}</math></li> <li>2. Time : 96 hrs</li> <li>3. Measure VSWR<sub>C</sub> after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>1. No visual damage</li> <li>2. VSWR satisfy</li> </ol>
6	ESD	<ol style="list-style-type: none"> <li>1. ESD Level : 8KV</li> <li>2. Mode : Contact discharge</li> <li>3. Number of cycle : 100</li> </ol> <p>※ Used Ref test PCB.</p>	<ol style="list-style-type: none"> <li>1. No visual damage</li> <li>2. VSWR satisfy</li> </ol>

# 5. SOLDERING RECOMMENDATIONS

## 5.1. Reflow Soldering Profile

### A. Non Pb free



### B. Pb free

